Dr SATYANARAYAN

List of Publications by Year
in descending order

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20
papers

324
citations

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docs citations

20
times ranked

289
citing authors

#	Article	IF	Citations
1	Reactive wetting, evolution of interfacial and bulk IMCs and their effect on mechanical properties of eutectic Snâ€"Cu solder alloy. Advances in Colloid and Interface Science, 2011, 166, 87-118.	7.0	75
2	A Review of the Performance and Characterization of Conventional and Promising Thermal Interface Materials for Electronic Package Applications. Journal of Electronic Materials, 2019, 48, 7623-7634.	1.0	55
3	Wettability of root canal sealers on intraradicular dentine treated with different irrigating solutions. Journal of Dentistry, 2013, 41, 556-560.	1.7	45
4	Effect of cooling rate during solidification of Snâ€"9Zn lead-free solder alloy on its microstructure, tensile strength and ductileâ€"brittle transition temperature. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2012, 533, 64-70.	2.6	36
5	Welding of Sn and Cu plates using controlled underwater shock wave. Journal of Materials Processing Technology, 2017, 245, 300-308.	3.1	25
6	Underwater shock wave weldability window for Sn-Cu plates. Journal of Materials Processing Technology, 2019, 267, 152-158.	3.1	18
7	Wetting behaviour and interfacial microstructure of Snâ€"Agâ€"Zn solder alloys on nickel coated aluminium substrates. Materials Science and Technology, 2011, 27, 1157-1162.	0.8	14
8	Effect of temperature and substrate surface texture on wettability and morphology of IMCs between Snâ€"0.7Cu solder alloy and copper substrate. Journal of Materials Science: Materials in Electronics, 2012, 23, 1664-1672.	1.1	12
9	Effect of reflow temperature and substrate roughness on wettability, IMC growth and shear strength of SAC387/Cu bonds. Journal of Materials Science: Materials in Electronics, 2014, 25, 864-872.	1.1	9
10	Spreading Behavior and Evolution of IMCs During Reactive Wetting of SAC Solders on Smooth and Rough Copper Substrates. Journal of Electronic Materials, 2013, 42, 2696-2707.	1.0	8
11	Effect of Purging Gas on Wetting Behavior of Sn-3.5Ag Lead-Free Solder on Nickel-Coated Aluminum Substrate. Journal of Materials Engineering and Performance, 2013, 22, 723-728.	1.2	7
12	Reactive wetting of Snâ€"2.5Agâ€"0.5Cu solder on copper and silver coated copper substrates. Journal of Materials Science: Materials in Electronics, 2013, 24, 1714-1719.	1.1	5
13	Solder joint reliability of Snâ€"0Â·7Cu and Snâ€"0Â·3Agâ€"0Â·7Cu lead-free solder alloys solidified on copper substrates with different surface roughnesses. Materials Science and Technology, 2013, 29, 1430-1440.	0.8	4
14	Wetting Characteristics of Sn-0.7Cu Lead-Free Solder Alloy on Copper Substrates. Materials Science Forum, 2012, 710, 569-574.	0.3	3
15	Wetting Behavior and Evolution of Microstructure of Snâ€"3.5Ag Solder Alloy on Electroplated 304 Stainless Steel Substrates. Transactions of the Indian Institute of Metals, 2012, 65, 713-717.	0.7	3
16	The Effect of Thermal Ageing on Solder/Substrate Interfacial Microstructures During Reflow of Snâ€"37Pb and Snâ€"3Agâ€"0.5Cu. Transactions of the Indian Institute of Metals, 2019, 72, 1545-1549.	0.7	2
17	Effect of Cooling Medium on Microstructure, Impact and Hardness Properties of Alâ€"15Sn Alloy. Transactions of the Indian Institute of Metals, 2019, 72, 1941-1947.	0.7	2
18	Solder Joint Reliability of Sn-Cu and Sn-Ag-Cu Lead-Free Solder Alloys Solidified on Copper Substrates with Different Surface Roughnesses. Materials Science Forum, 2015, 830-831, 265-269.	0.3	1

#	ARTICLE	IF	CITATIONS
19	A review on effect of alloying elements and heat treatment on properties of Alâ€¯â^’â€¯Sn alloy. Materials Today: Proceedings, 2021, 35, 340-343.	0.9	0
20	An influence of substrate thickness on electrical conductivity of dip-soldered copper joints. Journal of Mines, Metals and Fuels, 2022, 69, 255.	0.0	0